

2. (Thrice Amended) A semiconductor integrated circuit comprising a microstrip structure comprising:

C1
CONT.
a signal line; and

a ground plate,

wherein at least one through hole is formed in said ground plate, and an inner wall of said through hole is only directly electrically connected to said ground plate.

5. (Thrice Amended) A semiconductor integrated circuit comprising a microstrip structure comprising:

C2
a signal line; and

a ground plate,

wherein at least one through hole is formed in said signal line, and an inner wall of said through hole which is formed in said signal line is only directly electrically connected to said signal line, and

wherein at least one through hole is formed in said ground plate, and an inner wall of said through hole which is formed in said ground plate is only directly electrically connected to said ground plate.
